





Goals



500X INCREASE IN COMPUTE PERFORMANCE

SCALABLE COMPUTE & MEMORY

PACKAGING & INTERCONNECT FOR DENSITY & SCALE

FULL SOFTWARE STACK/PROGRAMMING MODEL



Compute Efficiency



High Performance Graphics



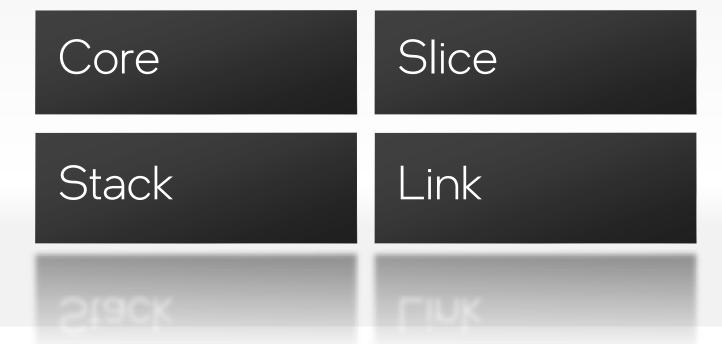
Scalability



Compute Density



Building Blocks









Compute Building Block of Xe HPC-based GPUs

8
Vector
Engines
512 bit
per engine

8
Matrix
Engines
4096 bit
per engine

Load/Store 512 B/CLK

Cache L1\$/ SLM (512KB), **|\$**



Vector Engine (ops/clk)

256 FP32

256 FP64

512 FP16





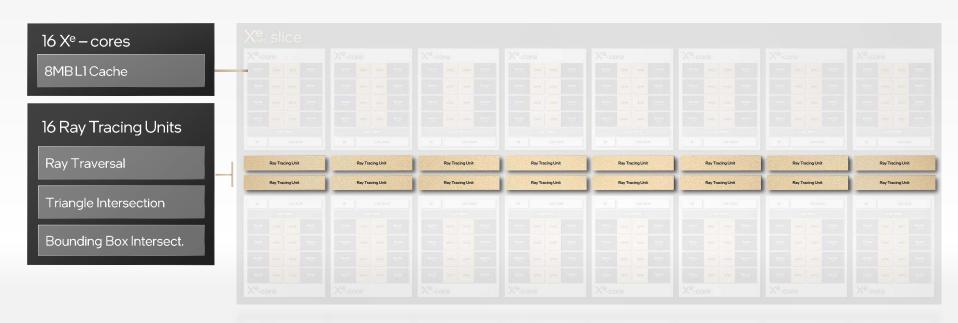


















Up to

4 Slices

64 Xe - cores

64 Ray Tracing Units

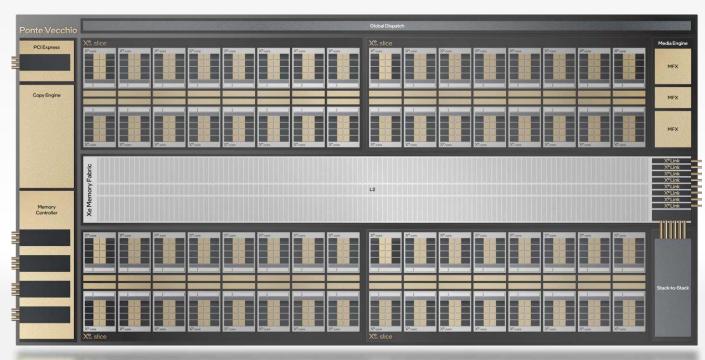
4 Hardware Contexts

L2 Cache

4 HBM2e controllers

1 Media Engine

8 X^e Links





8 Slices

128 Xe - cores

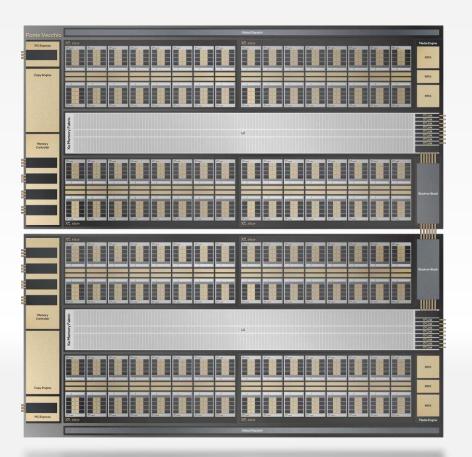
128 Ray Tracing Units

8 Hardware Contexts

2 Media Engines

8 HBM2e controllers

16 Xe Links

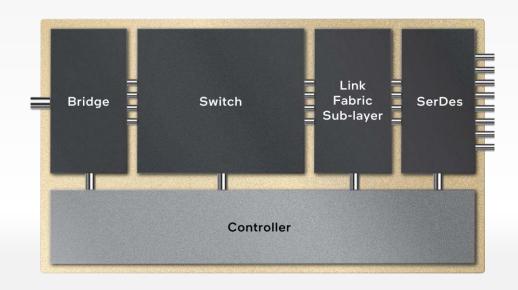




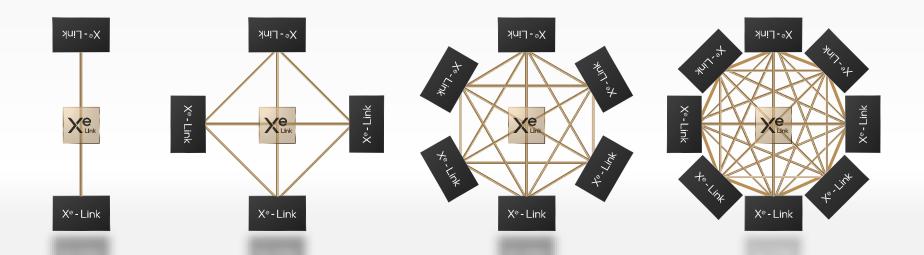
High Speed Coherent Unified Fabric (GPU to GPU)

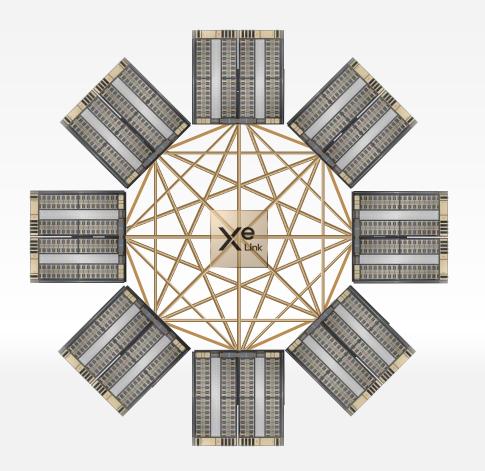
Load/Store, Bulk Data Transfer & Sync Semantics

Up to 8 Fully Connected GPUs through Embedded Switch



E Link for Scalability







8x System Compute Rates

Vector

Up to

32,768 FP64 Ops/CLK

Up to

32,768 FP32 Ops/CLK Matrix

Upto

8x 262,144

TF32 Ops/CLK

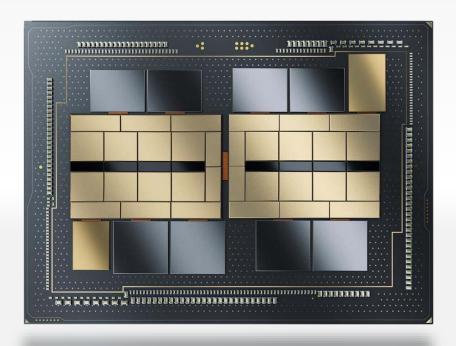
Upto

524,288

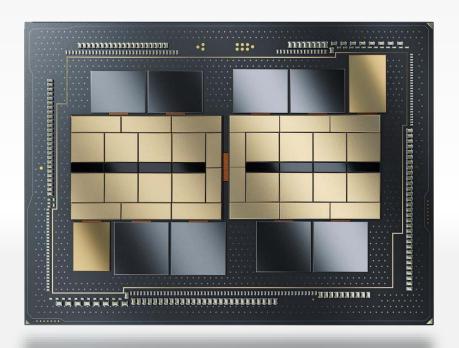
BF16 Ops/CLK

Upto

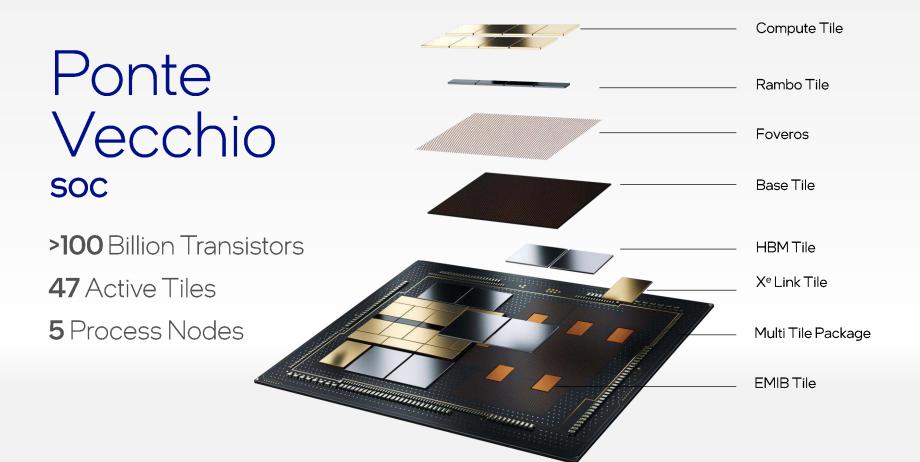
8x 1,048,576 INT8 Ops/CLK







New Verification Methodology New **Software** New Reliability Methodology New Signal Integrity Techniques New Interconnects New Power Delivery Technology New Packaging Technology New I/O Architecture New **Memory Architecture** New IP Architecture New **SOC Architecture**



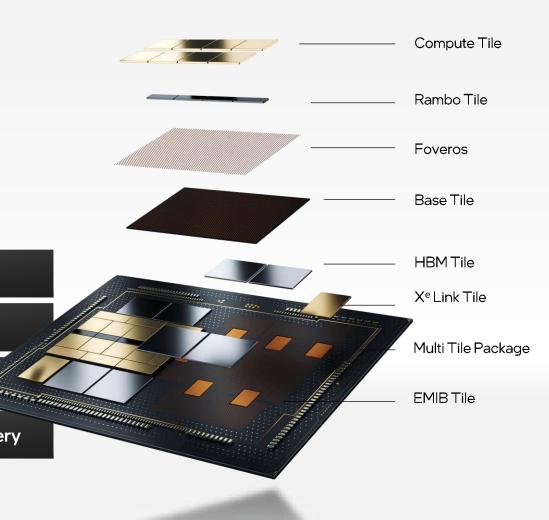
Key Challenges

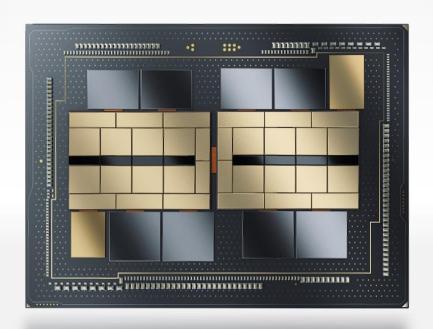
Scale of Integration

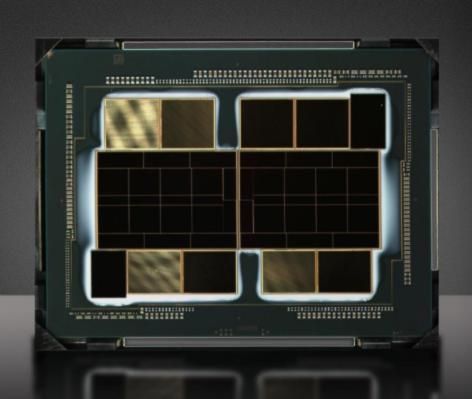
Foveros Implementation

Verification Tools & Methods

Signal Integrity, Reliability & Power Delivery









Compute Tiles

Per Tile

8

X^e-cores

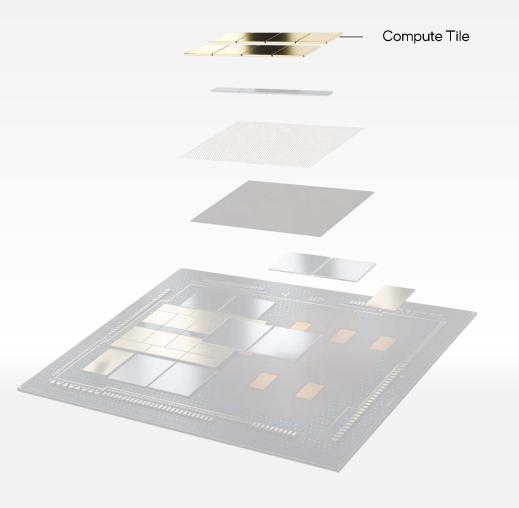
Built on TSMC N5

4MB
Per Tile

Bump Pitch

36um

Foveros



Base Tile

Built on Intel 7
FOVEROS

Area 640mm²

640mm²

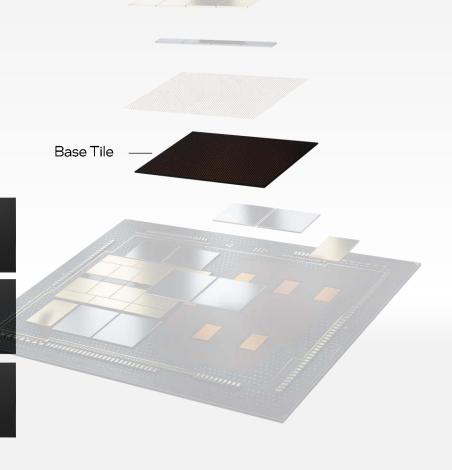
Host Interface PCIe

Gen5

MDFI

HBM2e

EMIB



X^e Link Tile

Per Tile

8 Xe Links

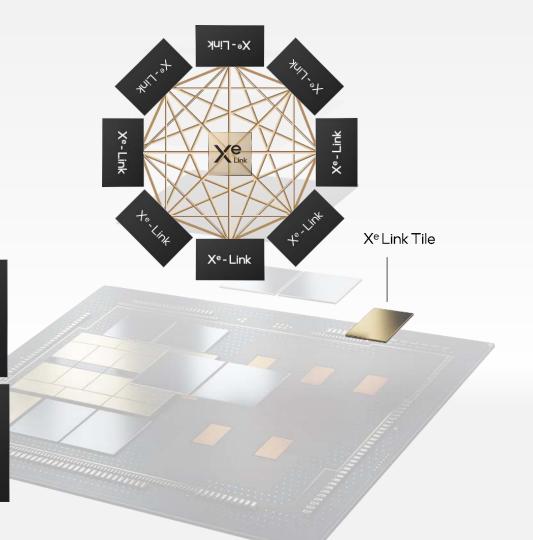
8 ports
Embedded
Switch

Built on TSMC N7

Up to

90G

Serdes



Accelerated Compute Systems

Ponte Vecchio x4 Subsystem with Xe Links

+ 2S Sapphire Rapids

Ponte Vecchio x4 Subsystem with Xe Links

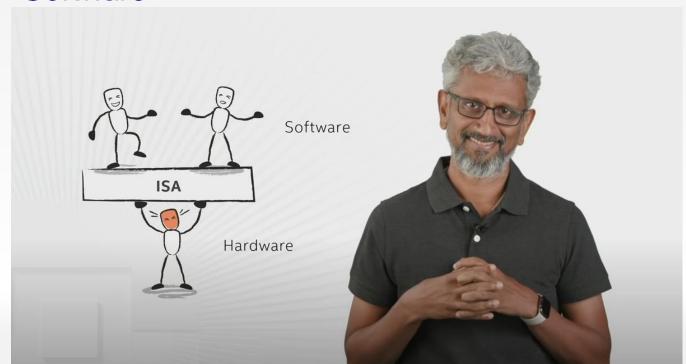
Ponte Vecchio OAM







Software



Raja Koduri, Intel - "No Transistor Left Behind" Hot Chips 2020 Keynote



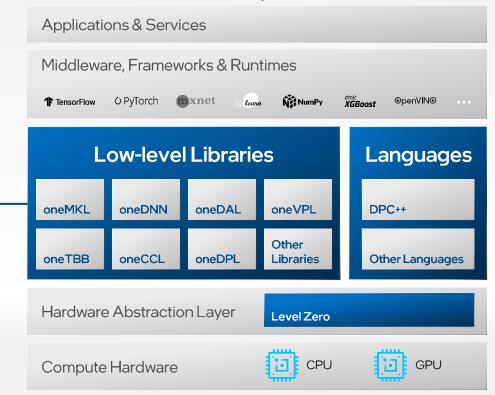
Open, Standards-Based Unified Software Stack

Freedom from proprietary programming models

Full performance from the hardware

Piece of mind for developers

CPU & XPU-Optimized Stack

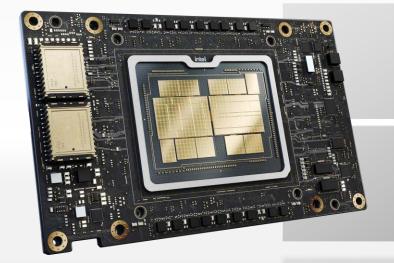


Execution Progress

A0 Silicon Current Status

>45 TFLOPS

FP32 Throughput



>5TBps

Memory Fabric Bandwidth

>2TBps

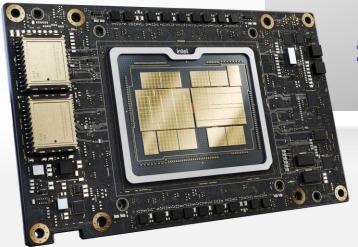
Connectivity Bandwidth

Execution Progress

A0 Silicon Current Status

> 43,000 img/sec

Inference



> 3,400 img/sec

Training

Resnet 50 performance

The vision 2 years ago...



Leadership Performance for HPC/AI

Connectivity to drive scaleup and scale out

Unified Programming Model powered with one API

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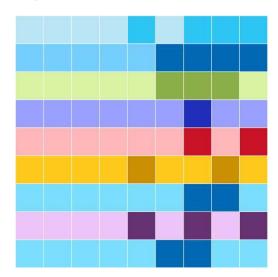
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Fig. 7



"Something is going to happen."
"What is going to happen?"
"Something _____."

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